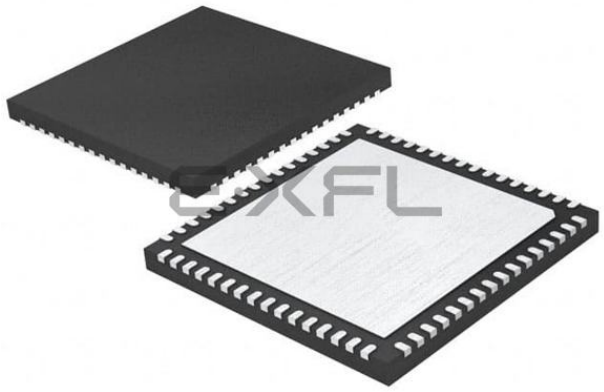

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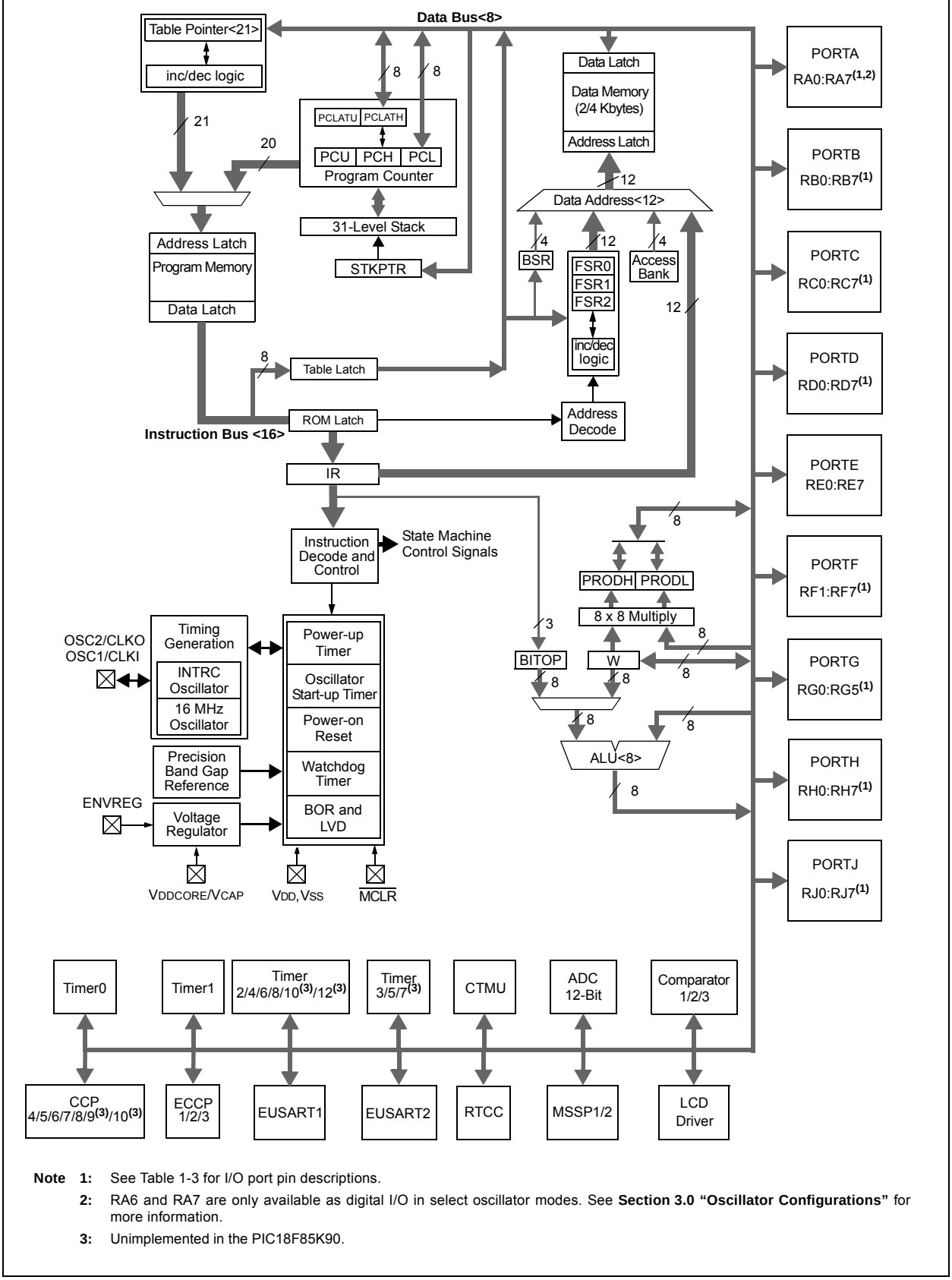
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (64K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f67k90-i-mr

FIGURE 1-2: PIC18F8XK90 (80-PIN) BLOCK DIAGRAM



Note 1: See Table 1-3 for I/O port pin descriptions.

2: RA6 and RA7 are only available as digital I/O in select oscillator modes. See **Section 3.0 "Oscillator Configurations"** for more information.

3: Unimplemented in the PIC18F85K90.

4.3 Sleep Mode

The power-managed Sleep mode in the PIC18F87K90 family of devices is identical to the legacy Sleep mode offered in all other PIC devices. It is entered by clearing the IDLEN bit (the default state on device Reset) and executing the SLEEP instruction. This shuts down the selected oscillator (Figure 4-5). All clock source status bits are cleared.

Entering Sleep mode from any other mode does not require a clock switch. This is because no clocks are needed once the controller has entered Sleep. If the WDT is selected, the LF-INTOSC source will continue to operate. If the SOSC oscillator is enabled, it will also continue to run.

When a wake event occurs in Sleep mode (by interrupt, Reset or WDT time-out), the device will not be clocked until the clock source selected by the SCS<1:0> bits becomes ready (see Figure 4-6). Alternately, the device will be clocked from the internal oscillator block if either the Two-Speed Start-up or the Fail-Safe Clock Monitor is enabled (see **Section 28.0 "Special Features of the CPU"**). In either case, the OSTS bit is set when the primary clock is providing the device clocks. The IDLEN and SCS bits are not affected by the wake-up.

4.4 Idle Modes

The Idle modes allow the controller's CPU to be selectively shut down while the peripherals continue to operate. Selecting a particular Idle mode allows users to further manage power consumption.

If the IDLEN bit is set to a '1' when a SLEEP instruction is executed, the peripherals will be clocked from the clock source selected using the SCS<1:0> bits. The CPU, however, will not be clocked. The clock source status bits are not affected. This approach is a quick method to switch from a given Run mode to its corresponding Idle mode.

If the WDT is selected, the LF-INTOSC source will continue to operate. If the SOSC oscillator is enabled, it will also continue to run.

Since the CPU is not executing instructions, the only exits from any of the Idle modes are by interrupt, WDT time-out or a Reset. When a wake event occurs, CPU execution is delayed by an interval of TCSD (Parameter 38, Table 31-10) while it becomes ready to execute code. When the CPU begins executing code, it resumes with the same clock source for the current Idle mode. For example, when waking from RC_IDLE mode, the internal oscillator block will clock the CPU and peripherals (in other words, RC_RUN mode). The IDLEN and SCS bits are not affected by the wake-up.

While in any Idle mode or Sleep mode, a WDT time-out will result in a WDT wake-up to the Run mode currently specified by the SCS<1:0> bits.

FIGURE 4-5: TRANSITION TIMING FOR ENTRY TO SLEEP MODE

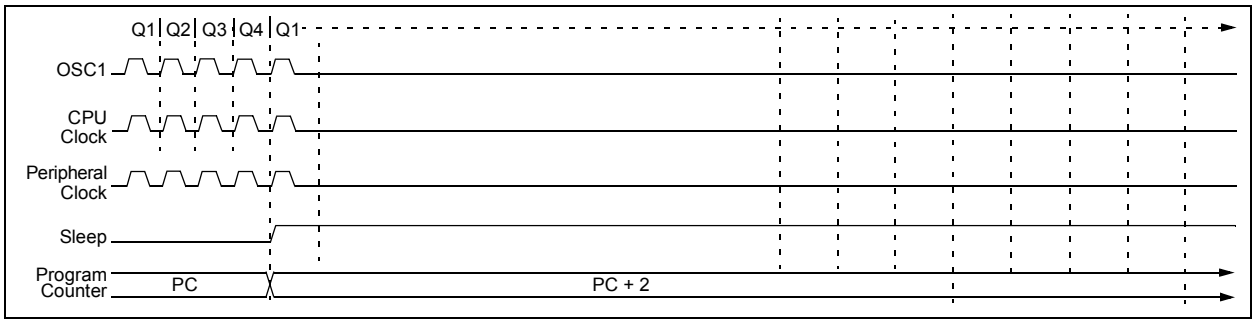
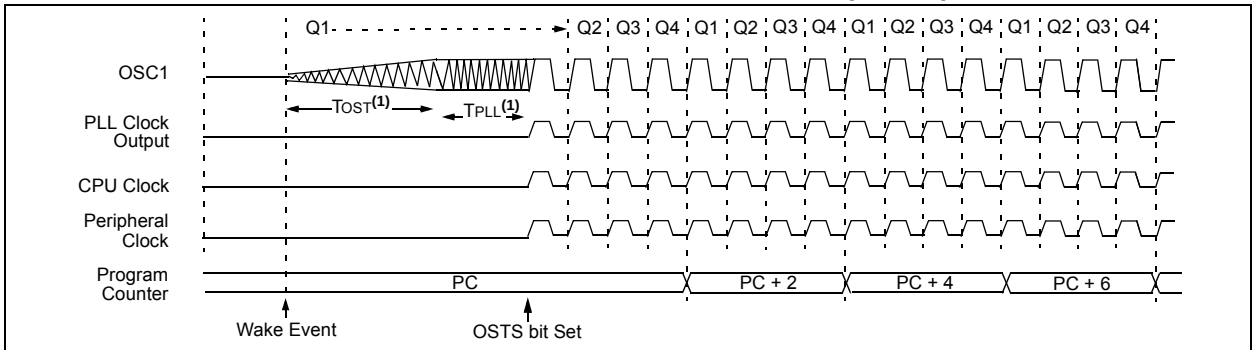


FIGURE 4-6: TRANSITION TIMING FOR WAKE FROM SLEEP (HSPLL)



Note 1: TOST = 1024 TOSC; TPLL = 2 ms (approx). These intervals are not shown to scale.

Example 9-3 shows the sequence to do a 16 x 16 unsigned multiplication. Equation 9-1 shows the algorithm that is used. The 32-bit result is stored in four registers (RES3:RES0).

EQUATION 9-1: 16 x 16 UNSIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L)
\end{aligned}
$$

EXAMPLE 9-3: 16 x 16 UNSIGNED MULTIPLY ROUTINE

```
    MOVF    ARG1L, W
    MULWF   ARG2L           ; ARG1L * ARG2L->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES1     ;
    MOVFF   PRODL, RES0     ;
;
    MOVF    ARG1H, W
    MULWF   ARG2H           ; ARG1H * ARG2H->
                            ; PRODH:PRODL
    MOVFF   PRODH, RES3     ;
    MOVFF   PRODL, RES2     ;
;
    MOVF    ARG1L, W
    MULWF   ARG2H           ; ARG1L * ARG2H->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
;
    MOVF    ARG1H, W        ;
    MULWF   ARG2L           ; ARG1H * ARG2L->
                            ; PRODH:PRODL
    MOVF    PRODL, W        ;
    ADDWF   RES1, F         ; Add cross
    MOVF    PRODH, W        ; products
    ADDWFC  RES2, F         ;
    CLRF    WREG            ;
    ADDWFC  RES3, F         ;
```

Example 9-4 shows the sequence to do a 16 x 16 signed multiply. Equation 9-2 shows the algorithm used. The 32-bit result is stored in four registers (RES3:RES0). To account for the sign bits of the arguments, the MSb for each argument pair is tested and the appropriate subtractions are done.

EQUATION 9-2: 16 x 16 SIGNED MULTIPLICATION ALGORITHM

$$
\begin{aligned}
RES3:RES0 &= ARG1H:ARG1L \bullet ARG2H:ARG2L \\
&= (ARG1H \bullet ARG2H \bullet 2^{16}) + \\
&\quad (ARG1H \bullet ARG2L \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2H \bullet 2^{8}) + \\
&\quad (ARG1L \bullet ARG2L) + \\
&\quad (-1 \bullet ARG2H\langle 7 \rangle \bullet ARG1H:ARG1L \bullet 2^{16}) + \\
&\quad (-1 \bullet ARG1H\langle 7 \rangle \bullet ARG2H:ARG2L \bullet 2^{16})
\end{aligned}
$$

EXAMPLE 9-4: 16 x 16 SIGNED MULTIPLY ROUTINE

```
   MOVF    ARG1L, W
   MULWF   ARG2L        ; ARG1L * ARG2L ->
                        ; PRODH:PRODL
   MOVFF   PRODH, RES1 ;
   MOVFF   PRODL, RES0 ;
;
   MOVF    ARG1H, W
   MULWF   ARG2H        ; ARG1H * ARG2H ->
                        ; PRODH:PRODL
   MOVFF   PRODH, RES3 ;
   MOVFF   PRODL, RES2 ;
;
   MOVF    ARG1L, W
   MULWF   ARG2H        ; ARG1L * ARG2H ->
                        ; PRODH:PRODL
   MOVF    PRODL, W     ;
   ADDWF   RES1, F      ; Add cross
   MOVF    PRODH, W     ; products
   ADDWFC  RES2, F      ;
   CLRF    WREG         ;
   ADDWFC  RES3, F      ;
;
   MOVF    ARG1H, W     ;
   MULWF   ARG2L        ; ARG1H * ARG2L ->
                        ; PRODH:PRODL
   MOVF    PRODL, W     ;
   ADDWF   RES1, F      ; Add cross
   MOVF    PRODH, W     ; products
   ADDWFC  RES2, F      ;
   CLRF    WREG         ;
   ADDWFC  RES3, F      ;
;
   BTFSS   ARG2H, 7     ; ARG2H:ARG2L neg?
   BRA     SIGN_ARG1    ; no, check ARG1
   MOVF    ARG1L, W     ;
   SUBWF   RES2         ;
   MOVF    ARG1H, W     ;
   SUBWFB  RES3         ;
SIGN_ARG1
   BTFSS   ARG1H, 7     ; ARG1H:ARG1L neg?
   BRA     CONT_CODE    ; no, done
   MOVF    ARG2L, W     ;
   SUBWF   RES2         ;
   MOVF    ARG2H, W     ;
   SUBWFB  RES3
;
CONT_CODE
   :
```

10.1 INTCON Registers

The INTCON registers are readable and writable registers that contain various enable, priority and flag bits.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt. This feature allows for software polling.

REGISTER 10-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE/GIEH:** Global Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked interrupts
0 = Disables all interrupts
When IPEN = 1:
1 = Enables all high-priority interrupts
0 = Disables all interrupts

bit 6 **PEIE/GIEL:** Peripheral Interrupt Enable bit
When IPEN = 0:
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts
When IPEN = 1:
1 = Enables all low-priority peripheral interrupts
0 = Disables all low-priority peripheral interrupts

bit 5 **TMR0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 overflow interrupt
0 = Disables the TMR0 overflow interrupt

bit 4 **INT0IE:** INT0 External Interrupt Enable bit
1 = Enables the INT0 external interrupt
0 = Disables the INT0 external interrupt

bit 3 **RBIE:** RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2 **TMR0IF:** TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INT0IF:** INT0 External Interrupt Flag bit
1 = The INT0 external interrupt occurred (must be cleared in software)
0 = The INT0 external interrupt did not occur

bit 0 **RBIF:** RB Port Change Interrupt Flag bit(1)
1 = At least one of the RB<7:4> pins changed state (must be cleared in software)
0 = None of the RB<7:4> pins have changed state

Note 1: A mismatch condition will continue to set this bit. Reading PORTB, and then waiting one additional instruction cycle, will end the mismatch condition and allow the bit to be cleared.

13.2 Timer1 Operation

The Timer1 module is an 8 or 16-bit incrementing counter that is accessed through the TMR1H:TMR1L register pair.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter. It increments on every selected edge of the external source.

Timer1 is enabled by configuring the TMR1ON and TMR1GE bits in the T1CON and T1GCON registers, respectively.

When SOSC is selected as a Crystal mode (by SOSCEL), the RC1/SOSCI/ECCP2/P2A/SEG32 and RC0/SOSCO/SCLKI pins become inputs. This means the values of TRISC<1:0> are ignored and the pins are read as '0'.

13.3 Clock Source Selection

The TMR1CS<1:0> and SOSCEN bits of the T1CON register are used to select the clock source for Timer1. Register 13-1 displays the clock source selections.

13.3.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected, the TMR1H:TMR1L register pair will increment on multiples of FOSC, as determined by the Timer1 prescaler.

13.3.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When enabled to count, Timer1 is incremented on the rising edge of the external clock input, T1CKI. Either of these external clock sources can be synchronized to the microcontroller system clock or they can run asynchronously.

When used as a timer with a clock oscillator, an external, 32.768 kHz crystal can be used in conjunction with the dedicated internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1 is enabled after a POR Reset
- Write to TMR1H or TMR1L
- Timer1 is disabled
- Timer1 is disabled (TMR1ON = 0)

When T1CKI is high, Timer1 is enabled (TMR1ON = 1) when T1CKI is low.

TABLE 13-1: TIMER1 CLOCK SOURCE SELECTION

TMR1CS1	TMR1CS0	SOSCEN	Clock Source
0	1	x	Clock Source (FOSC)
0	0	x	Instruction Clock (FOSC/4)
1	0	0	External Clock on T1CKI Pin
1	0	1	Oscillator Circuit on SOSCI/SOSCO Pins

REGISTER 17-16: ALRMWD: ALARM WEEKDAY VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 17-17: ALRMHR: ALARM HOURS VALUE REGISTER(1)

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour's Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

18.4.3 SETUP FOR PWM OPERATION

To configure the CCP module for PWM operation (with CCP4 as an example):

1. Set the PWM period by writing to the PR2 register.
2. Set the PWM duty cycle by writing to the CCPR4L register and CCP4CON<5:4> bits.
3. Make the CCP4 pin an output by clearing the appropriate TRIS bit.
4. Set the TMR2 prescale value, then enable Timer2 by writing to T2CON.
5. Configure the CCP4 module for PWM operation.

TABLE 18-7: REGISTERS ASSOCIATED WITH PWM AND TIMERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	75
RCON	IPEN	SBOREN	$\overline{CM}$	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	76
PIR4	CCP10IF(1)	CCP9IF(1)	CCP8IF	CCP7IF	CCP6IF	CCP5IF	CCP4IF	CCP3IF	77
PIE4	CCP10IE(1)	CCP9IE(1)	CCP8IE	CCP7IE	CCP6IE	CCP5IE	CCP4IE	CCP3IE	77
IPR4	CCP10IP(1)	CCP9IP(1)	CCP8IP	CCP7IP	CCP6IP	CCP5IP	CCP4IP	CCP3IP	77
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	78
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	78
TRISE	TRISE7	TRISE6	TRISE5	TRISE4	TRISE3	TRISE2	TRISE1	TRISE0	78
TRISH	TRISH7	TRISH6	TRISH5	TRISH4	TRISH3	TRISH2	TRISH1	TRISH0	78
TMR2	Timer2 Register								76
TMR4	Timer4 Register								82
TMR6	Timer6 Register								81
TMR8	Timer8 Register								81
PR2	Timer2 Period Register								76
PR4	Timer4 Period Register								82
PR6	Timer6 Period Register								81
PR8	Timer8 Period Register								81
T2CON	—	T2OUTPS3	T2OUTPS2	T2OUTPS1	T2OUTPS0	TMR2ON	T2CKPS1	T2CKPS0	76
T4CON	—	T4OUTPS3	T4OUTPS2	T4OUTPS1	T4OUTPS0	TMR4ON	T4CKPS1	T4CKPS0	82
T6CON	—	T6OUTPS3	T6OUTPS2	T6OUTPS1	T6OUTPS0	TMR6ON	T6CKPS1	T6CKPS0	81
T8CON	—	T8OUTPS3	T8OUTPS2	T8OUTPS1	T8OUTPS0	TMR8ON	T8CKPS1	T8CKPS0	81
CCPR4L	Capture/Compare/PWM Register 4 Low Byte								82
CCPR4H	Capture/Compare/PWM Register 4 High Byte								82
CCPR5L	Capture/Compare/PWM Register 5 Low Byte								82
CCPR5H	Capture/Compare/PWM Register 5 High Byte								82
CCPR6L	Capture/Compare/PWM Register 6 Low Byte								82
CCPR6H	Capture/Compare/PWM Register 6 High Byte								82
CCPR7L	Capture/Compare/PWM Register 7 Low Byte								82
CCPR7H	Capture/Compare/PWM Register 7 High Byte								82
CCPR8L	Capture/Compare/PWM Register 8 Low Byte								80
CCPR8H	Capture/Compare/PWM Register 8 High Byte								80
CCPR9L(1)	Capture/Compare/PWM Register 9 Low Byte								80
CCPR9H(1)	Capture/Compare/PWM Register 9 High Byte								80
CCPR10L(1)	Capture/Compare/PWM Register 10 Low Byte								81

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PWM or Timer2/4/6/8.

Note 1: Unimplemented in devices with a program memory of 32 Kbytes (PIC18FX5K90).

There are two power modes designated as “Mode A” and “Mode B”. Mode A is set by the bits, LRLAP<1:0> and Mode B by LRLB<1:0>. The resistor ladder to use for Modes A and B are selected by the bits, LRLAP<1:0> and LRLBP<1:0>, respectively

Each ladder has a matching contrast control ladder, tuned to the nominal resistance of the reference ladder. This contrast control resistor can be controlled by LCDREF<5:3> (LCDCST<2:0>). Disabling the internal reference ladder results in all of the ladders being disconnected, allowing external voltages to be supplied.

To get additional current in High-Power mode, when LCDRL<7:6> (LRLAP<1:0>) = 11, both the medium and high-power resistor ladders are activated.

Whenever the LCD module is inactive (LCDA (LCDPS<5>) = 0), the reference ladder will be turned off.

20.3.2.1 Automatic Power Mode Switching

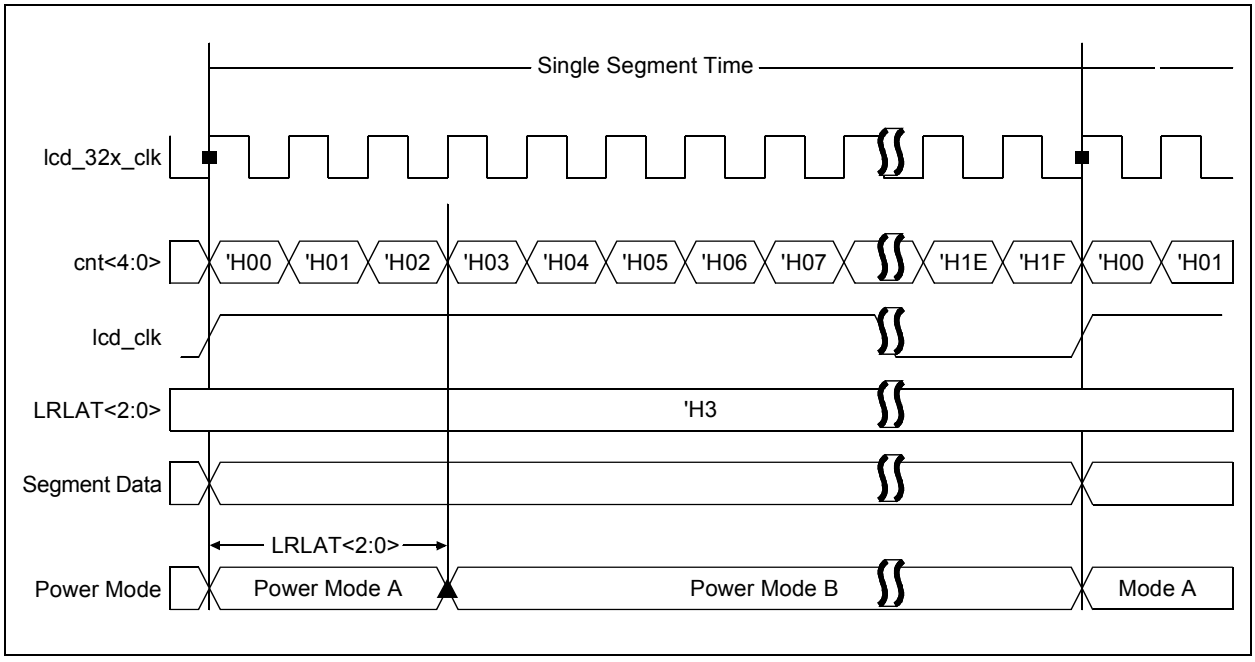
As an LCD segment is electrically only a capacitor, current is drawn only during the interval when the voltage is switching. To minimize total device current, the LCD reference ladder can be operated in a different power mode for the transition portion of the duration. This is controlled by the LCDRL register.

Mode A Power mode is active for a programmable time, beginning at the time when the LCD segment waveform is transitioning. The LCDRL<2:1> (LRLAT<2:0>) bits select how long, or if the Mode A is active. Mode B Power mode is active for the remaining time before the segments or commons change again.

As shown in Figure 20-5, there are 32 counts in a single segment time. Type-A can be chosen during the time when the wave form is in transition. Type-B can be used when the clock is stable or not in transition.

By using this feature of automatic power switching, using Type-A/Type-B, the power consumption can be optimized for a given contrast.

FIGURE 20-5: LCD REFERENCE LADDER POWER MODE SWITCHING DIAGRAM



20.7 LCD Frame Frequency

The rate at which the COM and SEG outputs change is called the LCD frame frequency.

TABLE 20-5: FRAME FREQUENCY FORMULAS

Multiplex	Frame Frequency =
Static	Clock Source/(4 x 1 x (LP<3:0> + 1))
1/2	Clock Source/(2 x 2 x (LP<3:0> + 1))
1/3	Clock Source/(1 x 3 x (LP<3:0> + 1))
1/4	Clock Source/(1 x 4 x (LP<3:0> + 1))

Note: Clock source is (FOSC/4)/8192, Timer1 Osc/32 or INTRC/32.

TABLE 20-6: APPROXIMATE FRAME FREQUENCY (IN Hz) USING FOSC AT 32 MHz, TIMER1 AT 32.768 kHz OR INTRC OSC

LP<3:0>	Static	1/2	1/3	1/4
1	125	125	167	125
2	83	83	111	83
3	62	62	83	62
4	50	50	67	50
5	42	42	56	42
6	36	36	48	36
7	31	31	42	31

20.8 LCD Waveform Generation

LCD waveform generation is based on the philosophy that the net AC voltage across the dark pixel should be maximized and the net AC voltage across the clear pixel should be minimized. The net DC voltage across any pixel should be zero.

The COM signal represents the time slice for each common, while the SEG contains the pixel data.

The pixel signal (COM-SEG) will have no DC component and can take only one of the two rms values. The higher rms value will create a dark pixel and a lower rms value will create a clear pixel.

As the number of commons increases, the delta between the two rms values decreases. The delta represents the maximum contrast that the display can have.

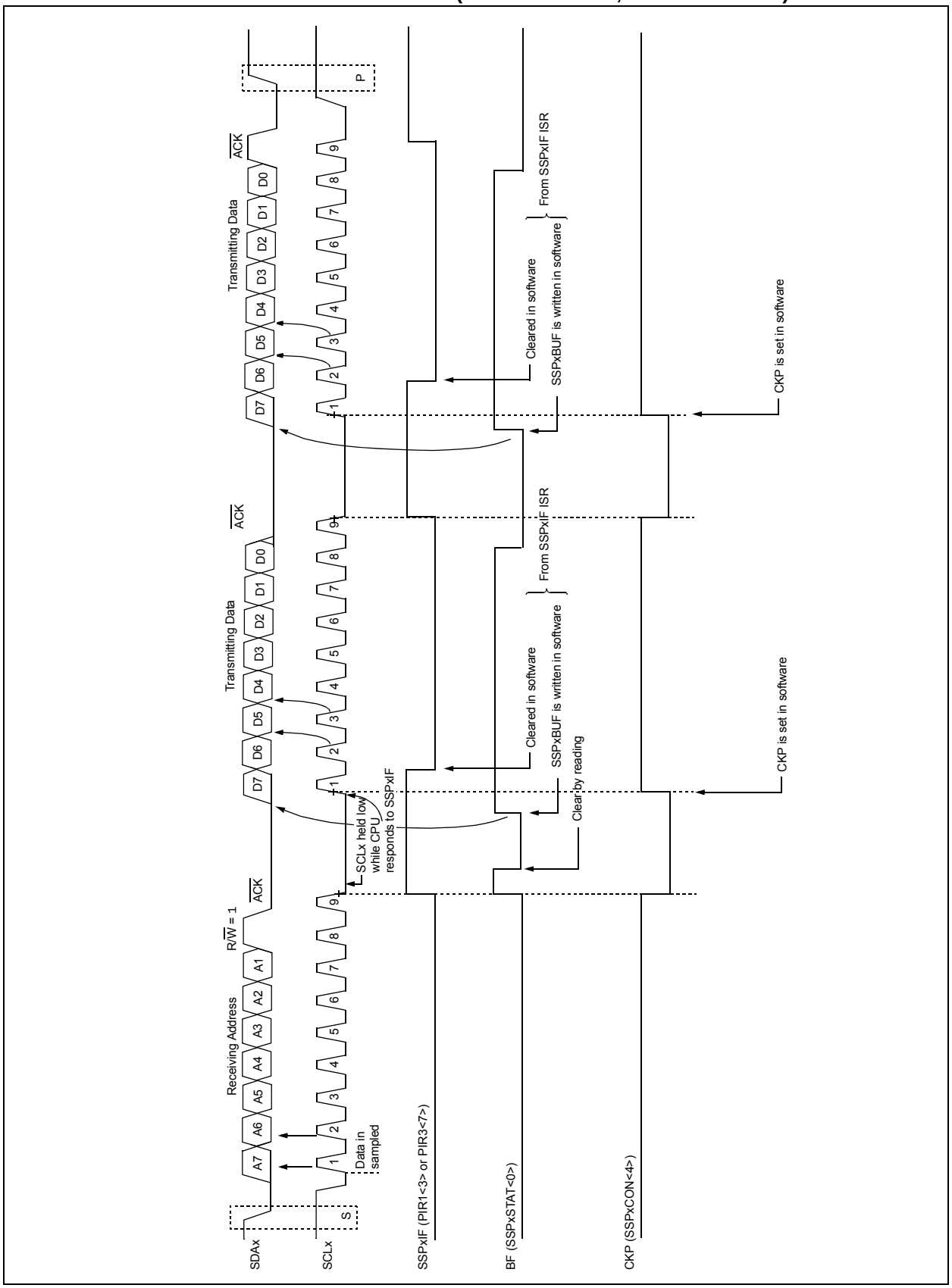
The LCDs can be driven by two types of waveforms: Type-A and Type-B. In a Type-A waveform, the phase changes within each common type, whereas a Type-B waveform's phase changes on each frame boundary. Thus, Type-A waveforms maintain 0 VDC over a single frame, whereas Type-B waveforms take two frames.

Note 1: If Sleep has to be executed with LCD Sleep enabled (SLPEN (LCDCON<6>) = 1), care must be taken to execute Sleep only when VDC on all the pixels is '0'.

2: When the LCD clock source is (FOSC/4)/8192, if Sleep is executed irrespective of the LCDCON<SLPEN> setting, the LCD goes into Sleep. Thus, take care to see that VDC on all pixels is '0' when Sleep is executed.

Figure 20-7 through Figure 20-17 provide waveforms for static, half-multiplex, one-third multiplex and quarter multiplex drives for Type-A and Type-B waveforms.

FIGURE 21-10: I²C™ SLAVE MODE TIMING (TRANSMISSION, 7-BIT ADDRESS)



27.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

The Charge Time Measurement Unit (CTMU) is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. By working with other on-chip analog modules, the CTMU can precisely measure time, capacitance and relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The module includes these key features:

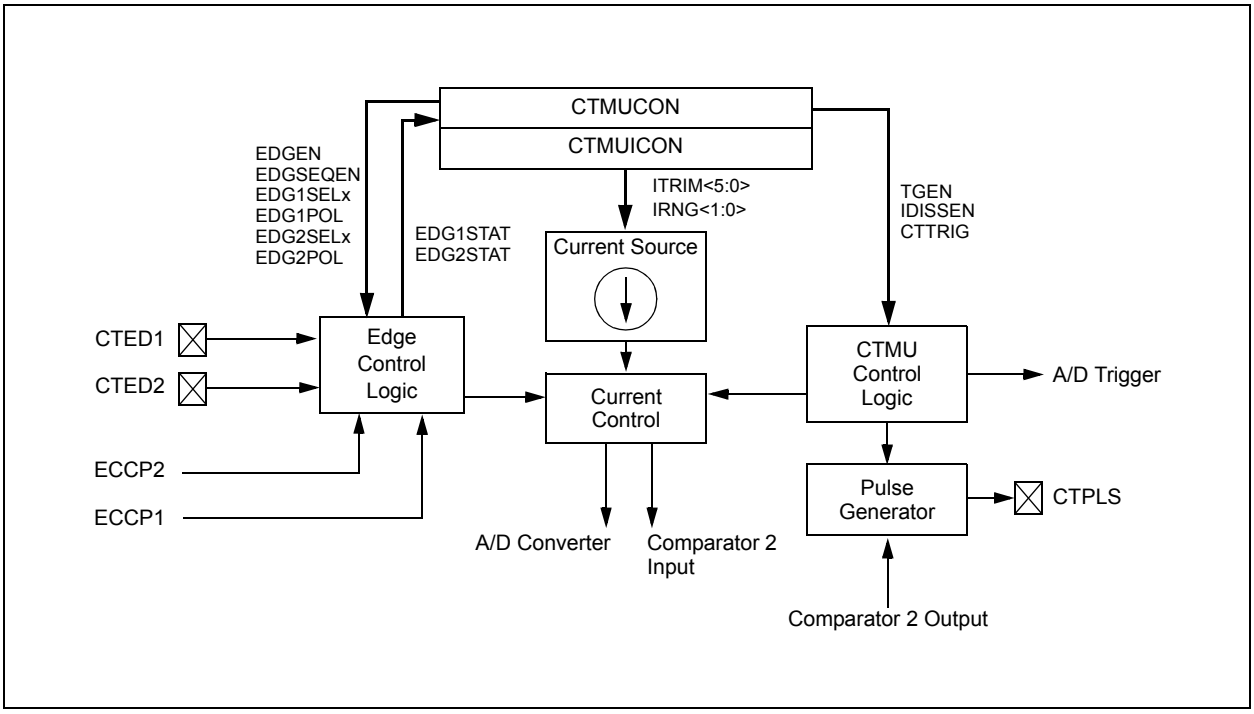
- Up to 24 channels available for capacitive or time measurement input
- On-chip precision current source
- Four-edge input trigger sources
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- Time measurement resolution of 1 nanosecond
- High-precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Accurate current source suitable for capacitive measurement

The CTMU works in conjunction with the A/D Converter to provide up to 24 channels for time or charge measurement, depending on the specific device and the number of A/D channels available. When configured for time delay, the CTMU is connected to one of the analog comparators. The level-sensitive input edge sources can be selected from four sources: two external inputs or the ECCP1/ECCP2 Special Event Triggers.

The CTMU special event can trigger the Analog-to-Digital Converter module.

Figure 27-1 provides a block diagram of the CTMU.

FIGURE 27-1: CTMU BLOCK DIAGRAM



27.1 CTMU Registers

The control registers for the CTMU are:

- CTMUCONH
- CTMUCONL
- CTMUICON

The CTMUCONH and CTMUCONL registers (Register 27-1 and Register 27-2) contain control bits for configuring the CTMU module edge source selection, edge source polarity selection, edge sequencing, A/D trigger, analog circuit capacitor discharge and enables. The CTMUICON register (Register 27-3) has bits for selecting the current source range and current source trim.

REGISTER 27-1: CTMUCONH: CTMU CONTROL HIGH REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 6 **Unimplemented:** Read as ‘0’

bit 5 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 4 **TGEN:** Time Generation Enable bit
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 3 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

bit 2 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 1 **IDISSEN:** Analog Current Source Control bit
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 0 **CTTRIG:** Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled

27.2 CTMU Operation

The CTMU works by using a fixed current source to charge a circuit. The type of circuit depends on the type of measurement being made.

In the case of charge measurement, the current is fixed and the amount of time the current is applied to the circuit is fixed. The amount of voltage read by the A/D becomes a measurement of the circuit's capacitance.

In the case of time measurement, the current, as well as the capacitance of the circuit, is fixed. In this case, the voltage read by the A/D is representative of the amount of time elapsed from the time the current source starts and stops charging the circuit.

If the CTMU is being used as a time delay, both capacitance and current source are fixed, as well as the voltage supplied to the comparator circuit. The delay of a signal is determined by the amount of time it takes the voltage to charge to the comparator threshold voltage.

27.2.1 THEORY OF OPERATION

The operation of the CTMU is based on the equation for charge:

$$C = I \bullet \frac{dV}{dT}$$

More simply, the amount of charge measured in coulombs in a circuit is defined as current in amperes (I) multiplied by the amount of time in seconds that the current flows (t). Charge is also defined as the capacitance in farads (C) multiplied by the voltage of the circuit (V). It follows that:

$$I \bullet t = C \bullet V$$

The CTMU module provides a constant, known current source. The A/D Converter is used to measure (V) in the equation, leaving two unknowns: capacitance (C) and time (t). The above equation can be used to calculate capacitance or time, by either the relationship using the known fixed capacitance of the circuit:

$$t = (C \bullet V)/I$$

or by:

$$C = (I \bullet t)/V$$

using a fixed time that the current source is applied to the circuit.

27.2.2 CURRENT SOURCE

At the heart of the CTMU is a precision current source, designed to provide a constant reference for measurements. The level of current is user-selectable across three ranges or a total of two orders of magnitude, with the ability to trim the output in ±2% increments (nominal). The current range is selected by the IRNG<1:0> bits (CTMUICON<1:0>), with a value of '00' representing the lowest range.

Current trim is provided by the ITRIM<5:0> bits (CTMUICON<7:2>). These six bits allow trimming of the current source in steps of approximately 2% per step. Half of the range adjusts the current source positively and the other half reduces the current source. A value of '000000' is the neutral position (no change). A value of '100000' is the maximum negative adjustment (approximately -62%) and '011111' is the maximum positive adjustment (approximately +62%).

27.2.3 EDGE SELECTION AND CONTROL

CTMU measurements are controlled by edge events occurring on the module's two input channels. Each channel, referred to as Edge 1 and Edge 2, can be configured to receive input pulses from one of the edge input pins (CTED1 and CTED2) or CCPx Special Event Triggers. The input channels are level-sensitive, responding to the instantaneous level on the channel rather than a transition between levels. The inputs are selected using the EDG1SEL and EDG2SEL bit pairs (CTMUCONL<3:2, 6:5>).

In addition to source, each channel can be configured for event polarity using the EDGE2POL and EDGE1POL bits (CTMUCONL<7,4>). The input channels can also be filtered for an edge event sequence (Edge 1 occurring before Edge 2) by setting the EDGSEQEN bit (CTMUCONH<2>).

27.2.4 EDGE STATUS

The CTMUCON register also contains two status bits, EDG2STAT and EDG1STAT (CTMUCONL<1:0>). Their primary function is to show if an edge response has occurred on the corresponding channel. The CTMU automatically sets a particular bit when an edge response is detected on its channel. The level-sensitive nature of the input channels also means that the status bits become set immediately if the channel's configuration is changed and matches the channel's current state.

The module uses the edge status bits to control the current source output to external analog modules (such as the A/D Converter). Current is only supplied to external modules when only one (not both) of the status bits is set. Current is shut off when both bits are either set or cleared. This allows the CTMU to measure current only during the interval between edges. After both status bits are set, it is necessary to clear them before another measurement is taken. Both bits should be cleared simultaneously, if possible, to avoid re-enabling the CTMU current source.

In addition to being set by the CTMU hardware, the edge status bits can also be set by software. This permits a user application to manually enable or disable the current source. Setting either (but not both) of the bits enables the current source. Setting or clearing both bits at once disables the source.

DECFSZ **Decrement f, Skip if 0**

Syntax: DECFSZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – 1 → dest,
skip if result = 0

Status Affected: None

Encoding:

0010	11da	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If the result is '0', the next instruction which is already fetched is discarded and a NOP is executed instead, making it a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 29.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    DECFSZ  CNT, 1, 1
        GOTO    LOOP
CONTINUE
```
Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT – 1
If CNT = 0;
PC = Address (CONTINUE)
If CNT ≠ 0;
PC = Address (HERE + 2)

DCFSNZ **Decrement f, Skip if Not 0**

Syntax: DCFSNZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) – 1 → dest,
skip if result ≠ 0

Status Affected: None

Encoding:

0100	11da	ffff	ffff

Description: The contents of register 'f' are decremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If the result is not '0', the next instruction which is already fetched is discarded and a NOP is executed instead, making it a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 29.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    DCFSNZ  TEMP, 1, 0
ZERO    :
NZERO   :
```
Before Instruction
TEMP = ?
After Instruction
TEMP = TEMP – 1,
If TEMP = 0;
PC = Address (ZERO)
If TEMP ≠ 0;
PC = Address (NZERO)

POP **Pop Top of Return Stack**

Syntax: POP

Operands: None

Operation: (TOS) → bit bucket

Status Affected: None

Encoding:

0000	0000	0000	0110

Description: The TOS value is pulled off the return stack and is discarded. The TOS value then becomes the previous value that was pushed onto the return stack. This instruction is provided to enable the user to properly manage the return stack to incorporate a software stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	POP TOS value	No operation

Example:
```
POP
GOTO    NEW
```
Before Instruction
TOS = 0031A2h
Stack (1 level down) = 014332h

After Instruction
TOS = 014332h
PC = NEW

PUSH **Push Top of Return Stack**

Syntax: PUSH

Operands: None

Operation: (PC + 2) → TOS

Status Affected: None

Encoding:

0000	0000	0000	0101

Description: The PC + 2 is pushed onto the top of the return stack. The previous TOS value is pushed down on the stack. This instruction allows implementing a software stack by modifying TOS and then pushing it onto the return stack.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	PUSH PC + 2 onto return stack	No operation	No operation

Example:
```
PUSH
```
Before Instruction
TOS = 345Ah
PC = 0124h

After Instruction
PC = 0126h
TOS = 0126h
Stack (1 level down) = 345Ah

29.2.3 BYTE-ORIENTED AND BIT-ORIENTED INSTRUCTIONS IN INDEXED LITERAL OFFSET MODE

Note: Enabling the PIC18 instruction set extension may cause legacy applications to behave erratically or fail entirely.

In addition to eight new commands in the extended set, enabling the extended instruction set also enables Indexed Literal Offset Addressing (**Section 6.6.1 "Indexed Addressing with Literal Offset"**). This has a significant impact on the way that many commands of the standard PIC18 instruction set are interpreted.

When the extended set is disabled, addresses embedded in opcodes are treated as literal memory locations: either as a location in the Access Bank (a = 0) or in a GPR bank designated by the BSR (a = 1). When the extended instruction set is enabled and a = 0, however, a file register argument of 5Fh or less is interpreted as an offset from the pointer value in FSR2 and not as a literal address. For practical purposes, this means that all instructions that use the Access RAM bit as an argument – that is, all byte-oriented and bit-oriented instructions, or almost half of the core PIC18 instructions – may behave differently when the extended instruction set is enabled.

When the content of FSR2 is 00h, the boundaries of the Access RAM are essentially remapped to their original values. This may be useful in creating backward compatible code. If this technique is used, it may be necessary to save the value of FSR2 and restore it when moving back and forth between C and assembly routines in order to preserve the Stack Pointer. Users must also keep in mind the syntax requirements of the extended instruction set (see **Section 29.2.3.1 "Extended Instruction Syntax with Standard PIC18 Commands"**).

Although the Indexed Literal Offset mode can be very useful for dynamic stack and pointer manipulation, it can also be very annoying if a simple arithmetic operation is carried out on the wrong register. Users who are accustomed to the PIC18 programming must keep in mind, that when the extended instruction set is enabled, register addresses of 5Fh or less are used for Indexed Literal Offset Addressing.

Representative examples of typical byte-oriented and bit-oriented instructions in the Indexed Literal Offset mode are provided on the following page to show how execution is affected. The operand conditions shown in the examples are applicable to all instructions of these types.

29.2.3.1 Extended Instruction Syntax with Standard PIC18 Commands

When the extended instruction set is enabled, the file register argument, 'f', in the standard byte-oriented and bit-oriented commands is replaced with the literal offset value, 'k'. As already noted, this occurs only when 'f' is less than or equal to 5Fh. When an offset value is used, it must be indicated by square brackets ("[ ]"). As with the extended instructions, the use of brackets indicates to the compiler that the value is to be interpreted as an index or an offset. Omitting the brackets, or using a value greater than 5Fh within the brackets, will generate an error in the MPASM™ Assembler.

If the index argument is properly bracketed for Indexed Literal Offset Addressing, the Access RAM argument is never specified; it will automatically be assumed to be '0'. This is in contrast to standard operation (extended instruction set disabled), when 'a' is set on the basis of the target address. Declaring the Access RAM bit in this mode will also generate an error in the MPASM Assembler.

The destination argument, 'd', functions as before.

In the latest versions of the MPASM Assembler, language support for the extended instruction set must be explicitly invoked. This is done with either the command line option, /y, or the PE directive in the source listing.

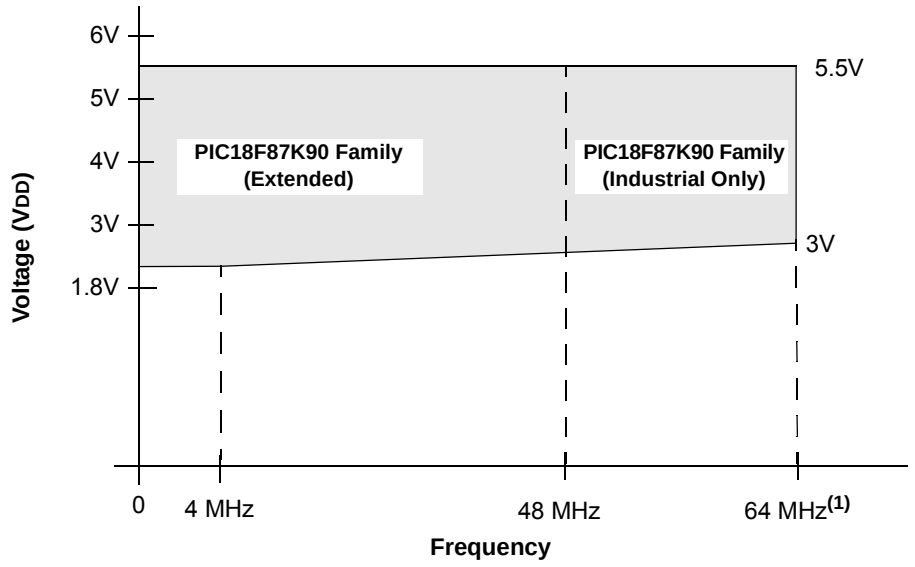
29.2.4 CONSIDERATIONS WHEN ENABLING THE EXTENDED INSTRUCTION SET

It is important to note that the extensions to the instruction set may not be beneficial to all users. In particular, users who are not writing code that uses a software stack may not benefit from using the extensions to the instruction set.

Additionally, the Indexed Literal Offset Addressing mode may create issues with legacy applications written to the PIC18 assembler. This is because instructions in the legacy code may attempt to address registers in the Access Bank below 5Fh. Since these addresses are interpreted as literal offsets to FSR2 when the instruction set extension is enabled, the application may read or write to the wrong data addresses.

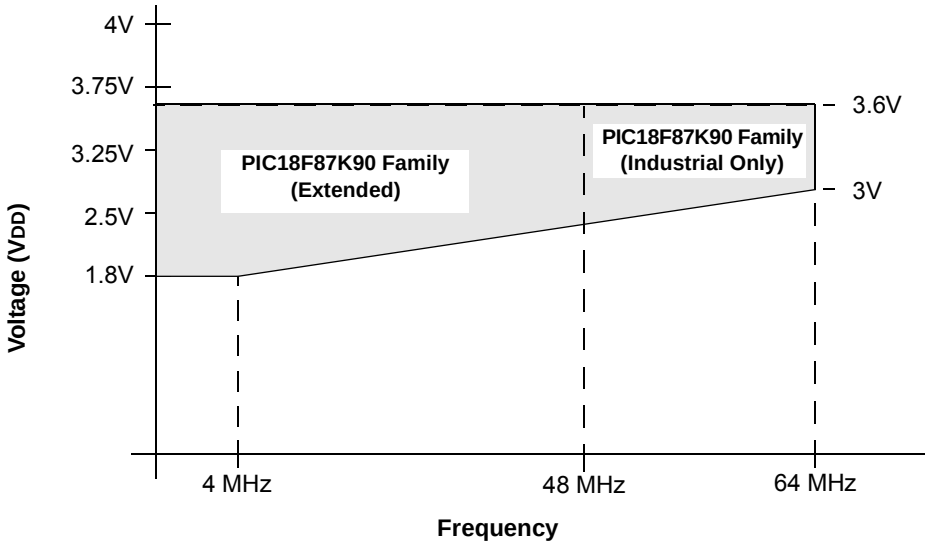
When porting an application to the PIC18F87K90 family, it is very important to consider the type of code. A large, re-entrant application that is written in C and would benefit from efficient compilation will do well when using the instruction set extensions. Legacy applications that heavily use the Access Bank will most likely not benefit from using the extended instruction set.

FIGURE 31-1: VOLTAGE-FREQUENCY GRAPH, REGULATOR ENABLED (INDUSTRIAL/EXTENDED)(1)



Note 1: FMAX = 64 MHz in all other modes. For VDD values, 1.8V to 3V, FMAX = (VDD – 1.72)/0.02 MHz.

FIGURE 31-2: VOLTAGE-FREQUENCY GRAPH, REGULATOR DISABLED (INDUSTRIAL/EXTENDED)(1,2)



Note 1: When the on-chip voltage regulator is disabled, VDD must be maintained so that VDD ≤ 3.6V.

2: For VDD values, 1.8V to 3V, FMAX = (VDD – 1.72)/0.02 MHz.

31.2 DC Characteristics: Power-Down and Supply Current PIC18F87K90 Family (Industrial/Extended) (Continued)

PIC18F87K90 Family		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD) Cont.(2,3)						
	All devices	3.7	8.5	µA	-40°C	VDD = 1.8V(4) Regulator Disabled	FOSC = 32 kHz(3) (**SEC_RUN** mode, SOSCSEL = 01)
		5.4	10	µA	+25°C		
		6.6	13	µA	+85°C		
		13	30	µA	+125°C		
	All devices	8.7	18	µA	-40°C	VDD = 3.3V(4) Regulator Disabled	
		10	20	µA	+25°C		
		12	23	µA	+85°C		
		25	60	µA	+125°C		
	All devices	60	160	µA	-40°C	VDD = 5V(5) Regulator Enabled	
		90	190	µA	+25°C		
		100	240	µA	+85°C		
		200	450	µA	+125°C		
	All devices	1.2	4	µA	-40°C	VDD = 1.8V(4) Regulator Disabled	FOSC = 32 kHz(3) (**SEC_IDLE** mode, SOSCSEL = 01)
		1.7	5	µA	+25°C		
		2.6	6	µA	+85°C		
		9	20	µA	+125°C		
	All devices	1.6	7	µA	-40°C	VDD = 3.3V(4) Regulator Disabled	
		2.8	9	µA	+25°C		
		4.1	10	µA	+85°C		
		17	40	µA	+125°C		
	All devices	60	150	µA	-40°C	VDD = 5V(5) Regulator Enabled	
		80	180	µA	+25°C		
		100	240	µA	+85°C		
		180	440	µA	+125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in a high-impedance state and tied to VDD or VSS, and all features that add delta current are disabled (such as WDT, SOSC oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

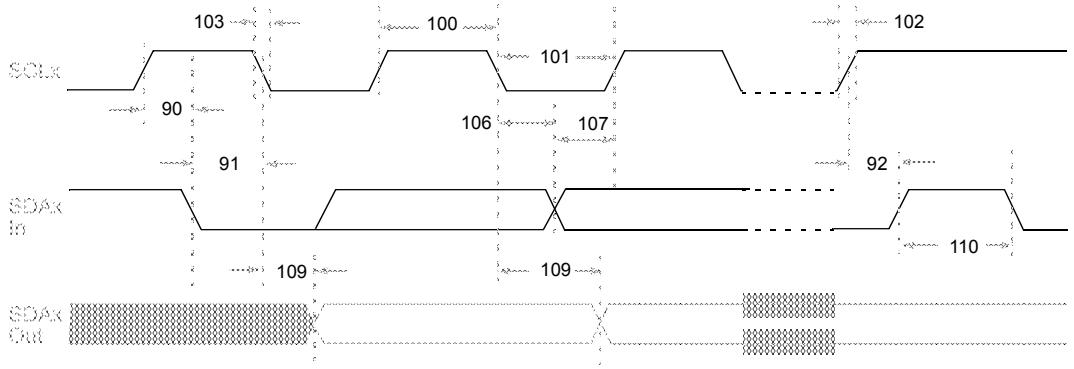
4: Voltage regulator disabled (ENVREG = 0, tied to VSS, $\overline{RETEN}$ (CONFIG1L<0>) = 1).

5: Voltage regulator enabled (ENVREG = 1, tied to VDD, SRETEN (WDTCON<4>) = 1 and $\overline{RETEN}$ (CONFIG1L<0>) = 0).

6: LCD glass is not connected; resistor current is not included.

7: 48 MHz maximum frequency at 125°C.

FIGURE 31-16: I²C™ BUS DATA TIMING



Note: Refer to Figure 31-3 for load conditions.

TABLE 31-19: I²C™ BUS DATA REQUIREMENTS (SLAVE MODE)

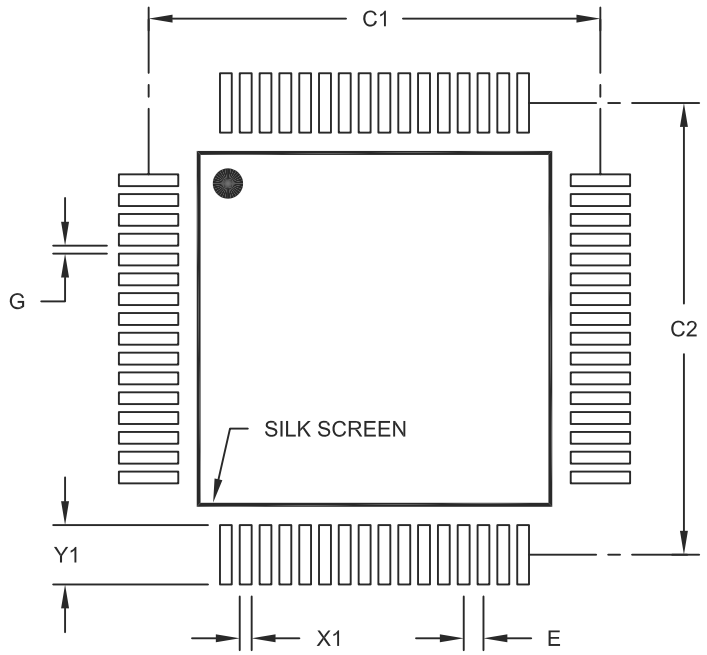
Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	4.0	—	µs	
			400 kHz mode	0.6	—	µs	
			MSSP module	1.5 TCY	—		
101	TLOW	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			MSSP module	1.5 TCY	—		
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1 CB	300	ns	CB is specified to be from 10 to 400 pF
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
91	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCLx to avoid unintended generation of Start or Stop conditions.

2: A Fast mode I²C™ bus device can be used in a Standard mode I²C bus system, but the requirement, TSU:DAT ≥ 250 ns, must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, TR max. + TSU:DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification), before the SCLx line is released.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085A